

Appl. No. 10/761,690

Amdt. dated November 23, 2005

Reply to Office action of August 23, 2005

10. (original) The system of Claim 9 wherein said pivoting member is a rotating vacuum coupling.
11. (original) The system of Claim 1 wherein said horizontal member is a solder ball mount.
- 12-18. (canceled)
19. (previously presented) A system for depositing solder onto a substrate, comprising:
- a horizontal member adapted to hold said solder;
  - a receiving member having a portion adapted to receive said substrate opposite said horizontal member; and a portion adapted to rotate independently with respect to the horizontal member; said rotatable receiving member comprises a base, a vertical member removably coupled to said base defining a T-shaped structure, said vertical member being adapted to act as an air conduit for selectively holding said substrate on said base;
  - a contact member having protruding portions adapted to selectively contact a substantially planar surface of the substrate on said receiving member, said contact member being positioned between said horizontal member and said receiving member,
- whereby said receiving member and said contact member functionally cooperate to hold said received substrate in a substantially planar position with respect to said horizontal member before and after said solder is deposited thereon.

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